Unit: mm

TOSHIBA Field Effect Transistor Silicon P/N-Channel MOS Type (P-Channel N-Channel Ultra-High-Speed U-MOSIII)

# **TPC8406-H**

High Efficiency DC ∕ DC Converter Applications

Notebook PC Applications

Portable Equipment Applications

**CCFL Inverter Applications** 

• Small footprint due to a small and thin package

High speed switching

• Low drain-source ON-resistance: P-Channel RDS (ON) = 24 m $\Omega$  (typ.)

N-Channel RDS (ON) =  $22 \text{ m}\Omega$  (typ.)

• Small gate charge: P-Channel  $Q_{SW} = 9.7 \text{ nC (typ.)}$ 

N-Channel Qsw = 3.5 nC (typ.)

• High forward transfer admittance: P-Channel  $|Y_{fs}| = 13 \text{ S (typ.)}$ 

N-Channel  $|Y_{fs}| = 14 \text{ S (typ.)}$ 

• Low leakage current: P-Channel IDSS =  $-10 \mu A (VDS = -40 V)$ 

N-Channel IDSS =  $10 \mu A (VDS = 40 V)$ 

• Enhancement mode

: P-Channel  $V_{th}$  = -0.8 to -2.0 V ( $V_{DS}$  = -10 V,  $I_{D}$  = -1 mA)

: N-Channel  $V_{th} = 1.1 \text{ to } 2.3 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$ 

### Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rat	Unit		
	Symbol	P-Channel	N-Channel	Offic		
Drain-source voltage		V <sub>DSS</sub>	-40	40	V	
Drain-gate vol	tage (R <sub>GS</sub> = 20 kΩ)	$V_{DGR}$	-40	40	V	
Gate-source v	oltage	V <sub>GSS</sub>	±20	±20	V	
Drain current	DC (Note 1)	ΙD	-6.5	6.5	Α	
Dialii cuireiit	Pulse (Note 1)	I <sub>DP</sub>	-26	26	A	
Drain power dissipation	Single-device operation (Note 3a)	P <sub>D(1)</sub>	1.5	1.5		
(t = 10s) (Note 2a)	Single-device value at dual operation (Note 3b)	P <sub>D(2)</sub>	1.1	1.1	W	
Drain power dissipation	Single-device operation (Note 3a)	P <sub>D(1)</sub>	0.75	0.75	VV	
(t = 10s) (Note 2b)	Single-device value at dual operation (Note 3b)	P <sub>D(2)</sub>	0.45	0.45		
Single-pulse avalanche energy		E <sub>AS</sub>	19 (Note 4a)	19 (Note 4b)	mJ	
Avalanche cur	I <sub>AR</sub>	-6.5	6.5	Α		
Repetitive avalanche energy Single-device value at operation (Note 2a, 3b, 5)		E <sub>AR</sub>	0.08		mJ	
Channel temperature		T <sub>ch</sub>	150		°C	
Storage temper	erature range	T <sub>stg</sub>	-55 to 150		°C	

0.595TYP 1.27 5.0±0.2 5.0±0.

**GATE** 

DRAIN

DRAIN

5, 6

7, 8

2-6J1E

Weight: 0.085 g (typ.)

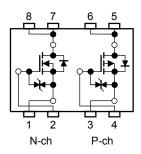
SOURCE

SOURCE

**GATE** 

JEDEC JEITA TOSHIBA

### **Circuit Configuration**



Note: For Notes 1 to 5, refer to the next page.

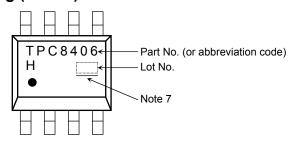
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

### **Thermal Characteristics**

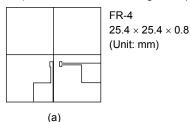
Characteristic	Symbol	Max	Unit	
Thermal resistance, channel to ambient (t = 10s) (Note 2a)	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	83.3	
	Single-device value at dual operation (Note 3b)	R <sub>th</sub> (ch-a) (2)	114	°C/W
Thermal resistance, channel to ambient	Single-device operation (Note 2a)	R <sub>th (ch-a) (1)</sub>	167	C/VV
(t = 10s) (Note 2b)	Single-device value at dual operation (Note 2b)	R <sub>th (ch-a) (2)</sub>	278	

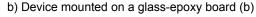
## Marking (Note 6)

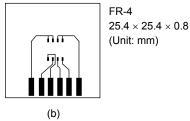


Note 1: The channel temperature should not exceed 150°C during use.

Note 2: a) Device mounted on a glass-epoxy board (a)





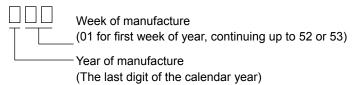


- Note 3: a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is applied to one device only.).
  - b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).

Note 4: a) 
$$V_{DD}=24$$
 V,  $T_{ch}=25^{\circ}C$  (initial), L = 0.5 mH,  $R_G=25$   $\Omega$ ,  $I_{AR}=6.5$  A b)  $V_{DD}=24$  V,  $T_{ch}=25^{\circ}C$  (initial), L = 0.5 mH,  $R_G=25$   $\Omega$ ,  $I_{AR}=6.5$  A

- Note 5: Repetitive rating: pulse width limited by maximum channel temperature
- Note 6: on the lower left of the marking indicates Pin 1.

\* Weekly code: (Three digits)



Note 7: A line under a Lot No. identifies the indication of product Labels.

Not underlined: [[Pb]]/INCLUDES > MCV

Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

# P-Channel Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cutoff curre	ent	I <sub>DSS</sub>	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}$			-10	μА
Drain agurag bro	akdowa voltago	V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-40	_	_	V
Drain-source breakdown voltage		V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-20	_	_	ľ
Gate threshold vo	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain-source ON	raciatanaa	D ()	$V_{GS} = -4.5 \text{ V}, I_D = -3.3 \text{ A}$	_	29	37	mO
Diain-source ON	-resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -3.3 A	_	24	30	mΩ
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -3.3 \text{ A}$	6.5	13	_	S
Input capacitance	e	C <sub>iss</sub>		_	1190	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	170	_	pF
Output capacitance		Coss		_	250	_	
	Rise time	t <sub>r</sub>	$V_{GS} = 0 \text{ V}$ $O_{GS} = 0 \text{ V}$	_	5	_	- ns
Considerate in an Alinea	Turn-on time	t <sub>on</sub>		_	12	_	
Switching time	Fall time	t <sub>f</sub>		_	12	_	
	Turn-off time	t <sub>off</sub>	Duty ≦ 1%, t <sub>W</sub> = 10 μs	_	43	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq -32 \text{ V}, V_{GS} = -10 \text{V}$ $I_D = -6.5 \text{ A}$		27	_	
			$\begin{aligned} V_{DD} &\simeq -32 \text{ V}, \text{ V}_{GS} = -5 \text{ V} \\ I_D &= -6.5 \text{ A} \end{aligned}$	_	15	_	nC
Gate-source charge 1		Q <sub>gs1</sub>	$V_{DD} \approx -32 \text{ V}, V_{GS} = -10 \text{ V}$ $I_{D} = -6.5 \text{ A}$	_	3.2	_	
Gate-drain ("Miller") charge		Q <sub>gd</sub>			8.1		
Gate switch char	ge	Q <sub>SW</sub>		_	9.7		

# Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	-26	Α
Forward voltage (diode)		V <sub>DSF</sub>	$I_{DR} = -6.5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

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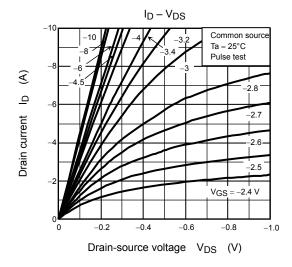
# N-channel Electrical Characteristics (Ta = 25°C)

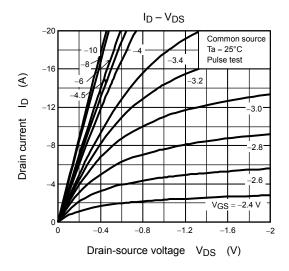
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cutoff current		I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V	_	_	10	μА
Drain source broa	akdowa voltago	V <sub>(BR) DSS</sub>	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	40	_	_	V
Drain-source breakdown voltage		V <sub>(BR) DSX</sub>	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	25	_	_	v
Gate threshold vo	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	1.1	_	2.3	V
Drain-source ON	rosistanco	Pro (ON)	$V_{GS} = 4.5 \text{ V}, I_D = 3.3 \text{ A}$	_	27	35	mΩ
Diam-source ON	-resistance	R <sub>DS</sub> (ON)	$V_{GS} = 10 \text{ V}, I_D = 3.3 \text{ A}$		22	27	1117.5
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_D = 3.3 \text{ A}$	7	14	_	S
Input capacitance	)	C <sub>iss</sub>		_	650	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	55	_	pF
Output capacitance		Coss		_	240	_	
	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10 \text{ V}}{\text{0 V}} \stackrel{\text{I}_{D} = 3.3 \text{ A}}{\text{0 V}_{OUT}} \stackrel{\text{V}_{D} = 3.3 \text{ A}}{\text{0 V}_{OUT}}$	_	3	_	
	Turn-on time	t <sub>on</sub>			9	_	
Switching time	Fall time	t <sub>f</sub>			2		ns
	Turn-off time	t <sub>off</sub>	Duty ≦ 1%, t <sub>W</sub> = 10 μs		18	_	
Total gate charge		0	$V_{DD} \simeq 32 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6.5 \text{ A}$	_	11	_	
(gate-source plus gate-drain)		Qg	$V_{DD} \simeq 32 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 6.5 \text{A}$	_	6.2	_	
Gate-source charge 1		Q <sub>gs1</sub>		_	2.1		nC
Gate-drain ("Miller") charge		Q <sub>gd</sub>	$V_{DD} \simeq 32 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6.5 \text{A}$	_	2.7	_	
Gate switch charg	Gate switch charge			_	3.5		

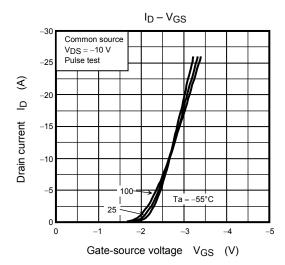
# Source-Drain Ratings and Characteristics (Ta = 25°C)

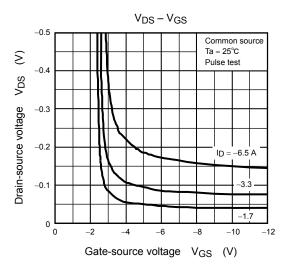
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	26	Α
Forward voltage (diode)		V <sub>DSF</sub>	$I_{DR} = 6.5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.2	V

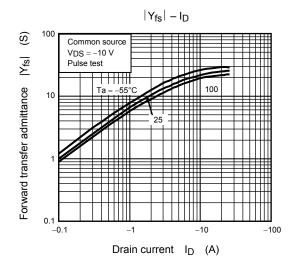
### P-Channel

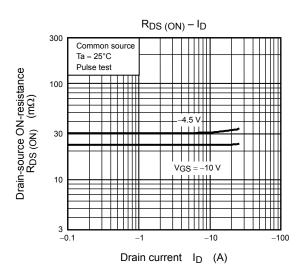




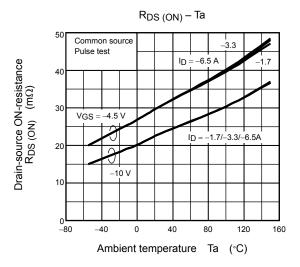


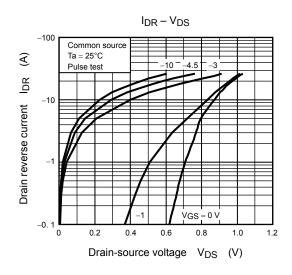


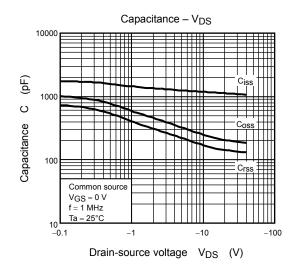


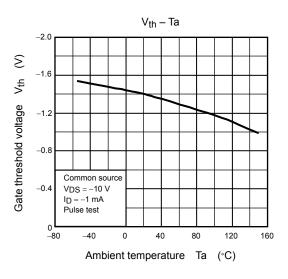


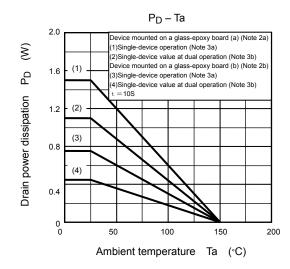
### **P-Channel**

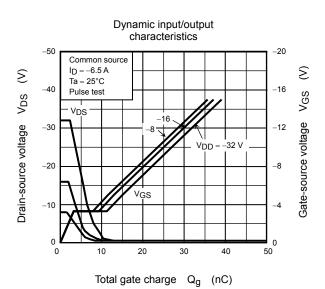






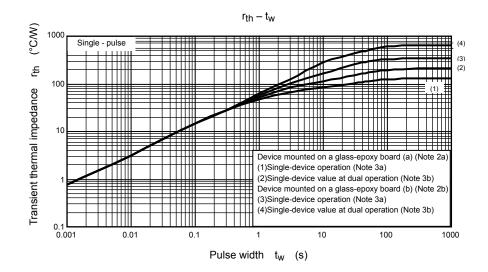




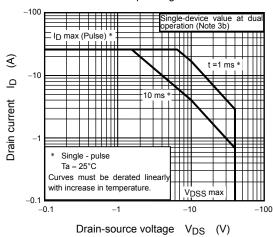


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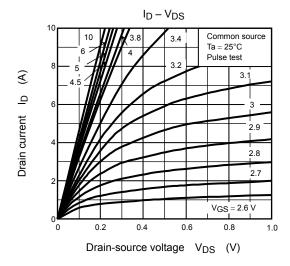
### **P-Channel**

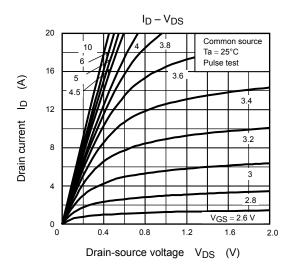


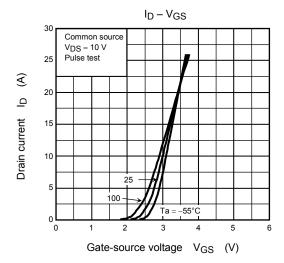


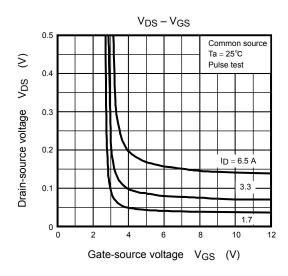


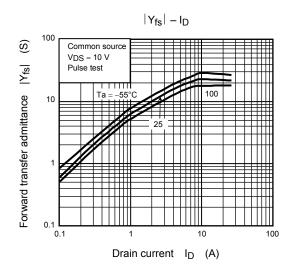
### **N-Channel**

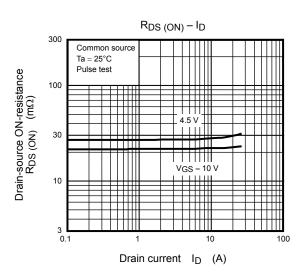




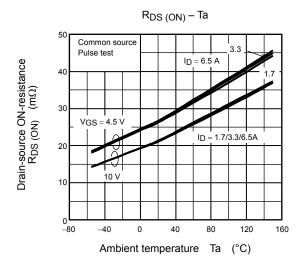


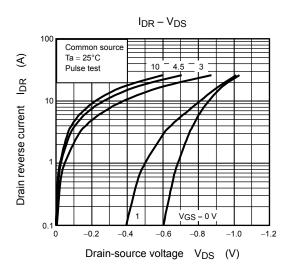


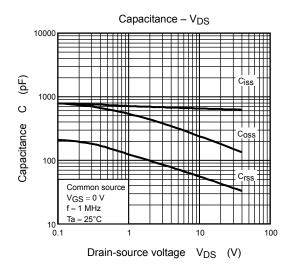


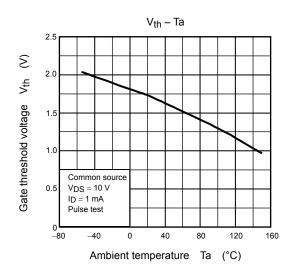


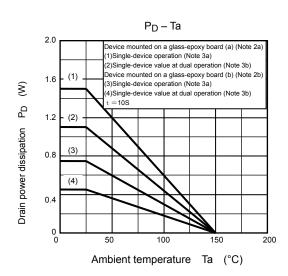
### **N-Channel**

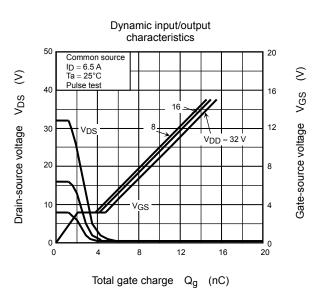






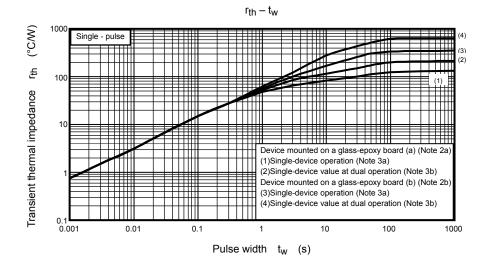


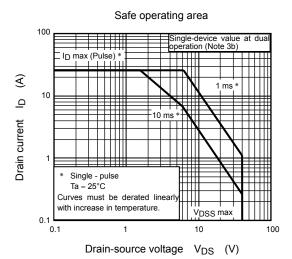




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### **N-Channel**





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